

Product features FI

340/31,8/SL/TO3

Semiconductor casing:	TO-3
Semiconductor mounted by:	Screw
Heat sink mounted by:	Srew-On
Finish	Blackened
Material	AlSiCu 3
Width [mm]:	40.5
Height [mm]:	31.8
Length [mm]:	46.0
Min. thermal resistance [K/W]:	4.0



Further information

Finger shaped heatsink from die-casting aluminium with or without hole pattern for semiconductor case TO3. Standard heights: 12,7; 19,1; 25,4; and 31,8 mm. Space saving construction. Turbulence in every installation position.

